



EUROPRACTICE I C S E R V I C E

UMC 0.18 μ , 0.13 μ , 0.11 μ , 65nm, 55nm, 40nm & 28nm CMOS PROTOTYPING AND SMALL VOLUMES

IMEC and UMC are offering Multi Project Wafer Services and small volume production in deep submicron CMOS technologies through the EUROPRACTICE IC Service

Features and Benefits

- Cost reduction on prototypes
- Monthly or regular MPW runs
- Flexible access to foundry wafer capacity for small volumes at UMC
- Distribution and full support of Faraday libraries and UMC libraries
- Deep Submicron RTL-to-Layout Service
- 0.18 μ , 0.13 μ , 0.11 μ , 65nm, 40nm and 28 nm CMOS logic and mixed signal/RF processes
- 0.18 μ CIS, 0.18 EFLASH
- Faraday's UMC-sponsored and UMC standard cell + I/O, memories, PLL and special IO available

0.18 μ eFlash + logic GII 2P6M (2)	L180 Logic + Mixed-Mode/RFCMOS 1P6M (1) (2)	L130E FSG Logic + MM/RFCMOS 1P8M (1) (2)	L110 Logic + MM/RFCMOS 1P8M (2)	65nm Logic + Mixed-Mode/RFCMOS 1P10M LowK (2)	40nm Logic/MM LP	28nm Logic/MM HPC
Double poly process MiM capacitors (1fF) Ono capacitors Triple well Hv P/NMOS (14V) MV P/NMOS (6.5V) Dual voltage (1.8V/3.3V)	Hipo resistor MiM Capacitor (1fF) Triple well Dual Voltage (1.8V / 3.3V) low / zero Vt 20kA RF metal	Hipo MiM capacitor (1, 1.5, 2fF) Triple Well HS (high speed) SP (st. perform) LL (low leakage) Dual Voltage (1.2V / 2.5V, 3.3V) Low Vt P/NMOS Zero Vt NMOS 20kA RF metal HG IO-device	HS (high speed) SP (st. perform) LL (low leakage) Dual Voltage (1.2V / 3.3V / 5V) Hipo resistor MiM capacitor (1, 1.5fF) Triple Well Low Vt P/NMOS Zero Vt NMOS 12, 20 or 40kA RF metal	Hipo res MiM capacitor (2fF) MOM capacitor Triple Well SP (std. perform.) LL (low leakage) Native Device NCAP capacitor Dual Voltage 1.0V, 1.2V / 1.8V, 2.5V, 3.3V 32 kA RF metal	P-Epi/P-Sub DNW ULVT, LVT, RVT, HVT MOM capacitor NCAP capacitor Diff resistor POresistors RW resistors 1.8V EXOR 2.5V I/O devices 12.5 KA or 34KA RF top metal	P-Epi/P-sub DNW ULVT, LVT, RVT, HVT, UHVT MOM capacitor NCAP 1.8V EXOR 2.5V I/O devices Diff resistors PO resistors RW resistors 14.5KA, 28KA or 34KA RF top metal
(1) Logic circuits can be fabricated in the MM process. Contact Europractice for more information (2) More technology flavors available on a case by case basis						

MPW runs in 2019	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
UMC L180 Logic GII, Mixed-Mode/RF		4		29			29			7		
UMC L180 EFLASH Logic GII ⁽¹⁾		25					8				11	
UMC CIS180 Image Sensor – CONV/ULTRA diode ⁽¹⁾				8					30			
UMC L130 Logic/Mixed-Mode/RF		18				24					4	
UMC L110AE Logic/Mixed-Mode/RF			11	22			8		9	28		
UMC L65N Logic/Mixed-Mode/RF - LL	2*		4	1*			1* + 22		30*		18	
UMC L65N Logic/Mixed-Mode/RF - SP	2*		4	1*			1* + 22				18	
UMC 40N Logic/Mixed-Mode – LP		25		29			1		2		18	
UMC 28N Logic/Mixed-Mode – HPC ⁽¹⁾		11				13		12			11	

* UMC L65N Logic/Mixed-Mode/RF - LL: Metallization recommendation on request. Redistribution to Aluminium. * = 32kA topmetal in development. Please check with us before tapeout.
* UMC L65N Logic/Mixed-Mode/RF - SP: Metallization recommendation on request. Redistribution to Aluminium. * = 32kA topmetal, LVT, MIM in development. 2.5V_OD3.3V not available.

All documentation & design kits available on :
For more information : mpc@imec.be

www.europractice-ic.com